## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

MAR 0 5 2001

In re the application of: Smith et al.

Serial No.:

09/757,073

Filed:

01/08/2001

Docket:

TI-22782B

Examiner:

E. Cameron

Art Unit:

1762

For:

Polyol-Based Method For Forming Thin Film Aerogels On Semiconductor

Substrates

## INFORMATION DISCLOSURE STATEMENT

February 21, 2001

Assistant Commissioner For Patents Washington, D. C. 20231

MAILING CERTIFICATE UNDER 37 C.F.R. I hereby certify that this correspondence is being leposite United States Postal Service as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington,

Examiner:

Applicants wish to bring to the attention of the Patent and Trademark Office the information noted on the enclosed PTO-1449. Many of these references were cited in related applications. References DI and DJ are in a foreign language. Their known relevance is that they were cited in a related application. English translations of the abstracts of references DI and DJ are included with the submission.

Copies of reference(s) AA - AW, BA - BV, CA - CX, DA - DE, DG - DU, and EE - EN are enclosed. Applicants believe that no fee is due. However, please charge any required fee to the deposit account of Texas Instruments Incorporated, Account No. 20-0668.

Respectfully submitted,

David Denker

Reg. No. 40,987

Texas Instruments Incorporated P. O. Box 655474, MS 3999 Dallas, Texas 75265 (972) 917-4388 Fax (972) 917-4418

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FORM PTO-1449 U.S. DEPARTMENT OF COMMERCE ATTY. DOCKET SERIAL NO. (REV. 7-80) PATENT AND TRADEMARK OFFICE NO. TI-22782B 09/757,073 LIST OF DOCUMENTS CITED BY APP (Use several sheets if necessary) APPLICANT Smith MAR 0 5 2001 FILING DATE 01/08/2001 U.S. PACENTIE DECUMENTS \*EXAMINER DOCUMENT FILING DATE CLASS INITIAL NUMBER DATE NAME F APPROPRIATE) CA 5,470,802 11/28/95 Gnade et al. 437 238 05/20/94 CB 5,472,913 12/05/95 Havemann et al. 437 08/05/94 195 CC 5,488,015 01/30/96 Havemann et al. 437 195 05/20/94 CD 5,494,858 02/27/96 Gnade et al. 437 231 06/07/94 04/02/96 CE 5,504,042 Cho et al. 437 247 06/23/94 **CF** 5,519,250 05/21/96 Numata 257 632 06/07/95 CG 06/04/96 Cho et al. 06/07/95 5,523,615 257 632 CH 5,525,857 06/11/96 Gnade et al. 313 309 08/19/94 CI 5,536,965 07/16/96 Beratan et al. 257 06/07/95 444 CJ 5,548,159 08/20/96 Jeng 257 05/23/95 634 CK 10/01/96 5,561,318 Gnade et al. 257 638 06/07/95 CL 5,656,848 08/12/97 Beratan et al. 257 446 06/07/95 CM 5,661,344 08/26/97 Havemann et al. 257 758 06/07/95 CN 5,723,368 3/3/98 Cho et al. 437 763 6/7/95 CO 5,736,425 04/07/98 Smith et al. 438 778 11/14/96 CP 5,747,880 5/5/98 Havemann et al. 257 759 11/18/96 5,750,415 5/12/98 Gnade et al. CQ 427 195 5/27/94 5,753,305 05/19/98 Smith et al. 427 CR 335 11/14/96 CS 5,789,819 08/04/98 Gnade et al. 06/07/95 CT 5,804,508 09/08/98 Gnade et al. 10/23/96 11/14/96 CU 5,807,607 09/15/98 Smith et al. CV5,847,443 12/08/98 Cho et al. 11/14/96 CW 5.858.871 01/12/99 06/13/96 Jeng CX 5,955,140 09/21/99 Smith et al. 11/14/96 FOREIGN PATENT DOCUMENTS TRANSLATION DOCUMENT NUMBER DATE COUNTRY **CLASS SUBCLASS** YES NO CY OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.) CZ **EXAMINER** DATE CONSIDERED EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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